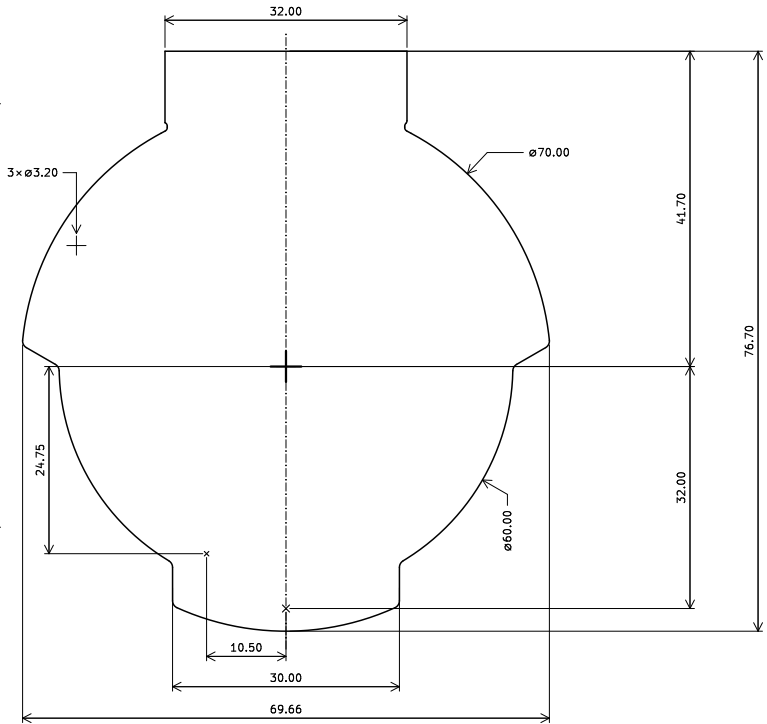


Top Fabrication (Scale 1:1)

Layer Stack Legend

Material	Layer	Thickness	Dielectric Material	Type	Gerber
F.Paste				Paste Mask	GBR
F.Silkscreen				Legend	GBR
F.Mask			Solder Resist	Solder Mask	GBR
Copper	L1 (Sig, PWR)	0.07mm (2oz)		Signal	GBR
Prepreg		0.18mm	FR-4	Dielectric	
Copper	L2 (GND)	0.035mm (1oz)		Internal Plane	GBR
Core		0.4mm	FR-4	Dielectric	
Copper	L3 (Sig, PWR)	0.035mm (1oz)		Signal	GBR
Prepreg		0.18mm	FR-4	Dielectric	
Copper	L4 (Sig, PWR)	0.035mm (1oz)		Signal	GBR
Core		0.4mm	FR-4	Dielectric	
Copper	L5 (GND)	0.035mm (1oz)		Internal Plane	GBR
Prepreg		0.18mm	FR-4	Dielectric	
Copper	L6 (Sig, PWR)	0.07mm (2oz)		Signal	GBR
B.Mask			Solder Resist	Solder Mask	GBR
B.Silkscreen				Legend	GBR
B.Paste				Paste Mask	GBR

Total thickness: 1.62mm
Note: external layer thicknesses are specified after plating.



FABRICATION NOTES (UNLESS OTHERWISE SPECIFIED)

- 1) OUTLINE DEFINED IN SEPARATE GERBER FILE WITH "Edge_Cuts.GBR" SUFFIX. DIMENSIONS OF CIRCUMSIZED RECTANGLE SHOWN ON THIS DWG FOR REF ONLY.
- 2) SEE SEPARATE DRILL FILES WITH ".DRL" SUFFIX FOR HOLE LOCATIONS. SELECTED HOLE LOCATIONS SHOWN ON THIS DWG FOR REF ONLY.
- 3) IMPEDANCE CONTROL REQUIRED. Microstrip 100-Ohm Differential (L1 ref. L2) 0.2032mm width, 0.28mm spacing
- 4) CONFIRM TRACE WIDTHS AND SPACINGS.
- 5) DESIGN GEOMETRY MINIMUM FEATURE SIZES:
 - TRACE WIDTH 0.20 mm
 - TRACE TO TRACE 0.20 mm
 - MIN. HOLE (PTH) 0.25 mm
 - MIN. HOLE (NPTH) 0.70 mm
 - ANNULAR RING 0.15 mm
 - COPPER TO HOLE 0.254 mm
 - COPPER TO EDGE 0.25 mm
 - HOLE TO HOLE 0.254 mm

All dimensions are in millimeters unless otherwise specified.